

### General Description :

The HMN4013A4 uses advanced trench technology and design to provide excellent  $R_{DS(ON)}$  with low gate charge. It can be used in a wide variety of applications. The package form is TO-252, which accords with the RoHS standard.

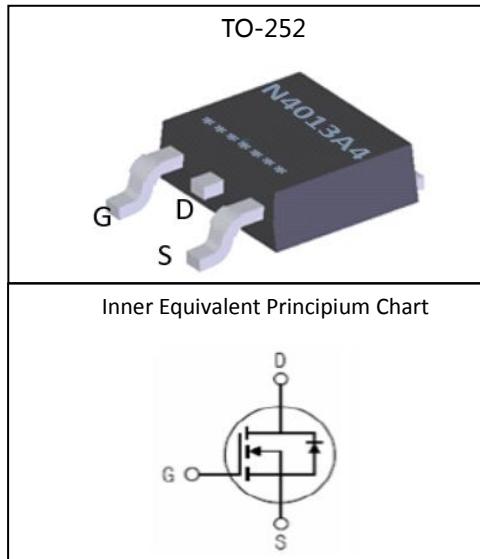
$V_{DSS}$	40	V
$I_D$	40	A
$P_D$	34	W
$R_{DS(ON)} \text{ TYPE}$	10.6	$\text{m}\Omega$

### Features :

- Fast Switching
- Low Gate Charge and  $R_{DS(on)}$
- Low Reverse transfer capacitances
- 100% Single Pulse avalanche energy Test

### Applications :

- Power switching application
- Hard switched and high frequency circuits
- Uninterruptible power supply



### Package Marking and Ordering Information:

Device Marking	Device	Device Package	Quantity
N4013A4	HMN4013A4	TO-252	2500 units

### Absolute Maximum Ratings ( TA= 25°C unless otherwise specified ):

Symbol	Parameter	Rating	Units
$V_{DSS}$	Drain-to-Source Voltage	40	V
$I_D$	Continuous Drain Current	40	A
	Continuous Drain Current $T_C = 100^\circ\text{C}$	28	A
$I_{DM}^{a1}$	Pulsed Drain Current	140	A
$V_{GS}$	Gate-to-Source Voltage	$\pm 20$	V
$E_{AS}^{a2}$	Single Pulse Avalanche Energy	80	mJ
$dv/dt^{a3}$	Peak Diode Recovery $dv/dt$	5.0	V/ns
$P_D$	Power Dissipation	34	W
$T_J, T_{stg}$	Operating Junction and Storage Temperature Range	150, -55 to 175	°C
$T_L$	Maximum Temperature for Soldering	300	°C

**Electrical Characteristics ( T<sub>c</sub> = 25°C unless otherwise specified ) :**

<b>OFF Characteristics</b>						
Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
V <sub>DSS</sub>	Drain to Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250μA	40	--	--	V
ΔBV <sub>DSS</sub> /ΔT <sub>J</sub>	BV <sub>DSS</sub> Temperature Coefficient	I <sub>D</sub> =250uA, Reference 25°C	--	0.1	--	V/°C
I <sub>DSS</sub>	Drain to Source Leakage Current	V <sub>DS</sub> = 40V, V <sub>GS</sub> = 0V, T <sub>j</sub> = 25°C	--	--	1	μA
		V <sub>DS</sub> = 40V, V <sub>GS</sub> = 0V, T <sub>j</sub> = 55°C	--	--	5	
I <sub>GSS(F)</sub>	Gate to Source Forward Leakage	V <sub>GS</sub> = +20V	--	--	100	nA
I <sub>GSS(R)</sub>	Gate to Source Reverse Leakage	V <sub>GS</sub> = -20V	--	--	-100	nA

<b>ON Characteristics</b>						
Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
R <sub>DS(ON)</sub>	Drain-to-Source On-Resistance	V <sub>GS</sub> =10V, I <sub>D</sub> =20A	--	10.6	13.0	mΩ
V <sub>GS(TH)</sub>	Gate Threshold Voltage	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250μA	1.0	1.5	2.5	V
Pulse width tp≤380μs, δ≤2%						

<b>Dynamic Characteristics</b>						
Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
C <sub>iss</sub>	Input Capacitance	V <sub>GS</sub> = 0V	--	750	--	pF
C <sub>oss</sub>	Output Capacitance	V <sub>DS</sub> = 20V	--	150	--	
C <sub>rss</sub>	Reverse Transfer Capacitance	f = 1.0MHz	--	80	--	

<b>Resistive Switching Characteristics</b>						
Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
t <sub>d(ON)</sub>	Turn-on Delay Time	I <sub>D</sub> = 20A V <sub>DS</sub> = 20V V <sub>GS</sub> = 10V R <sub>G</sub> = 3.0Ω R <sub>L</sub> = 1.0Ω	--	6.0	--	ns
tr	Rise Time		--	36.0	--	
t <sub>d(OFF)</sub>	Turn-Off Delay Time		--	29.0	--	
t <sub>f</sub>	Fall Time		--	7.0	--	
Q <sub>g</sub>	Total Gate Charge	I <sub>D</sub> = 20A V <sub>DD</sub> = 20V V <sub>GS</sub> = 10V	--	15	--	nC
Q <sub>gs</sub>	Gate to Source Charge		--	3	--	
Q <sub>gd</sub>	Gate to Drain ( "Miller" ) Charge		--	2.5	--	

Source-Drain Diode Characteristics						
Symbol	Parameter	Test Conditions	Rating			Units
			Min.	Typ.	Max.	
I <sub>S</sub>	Continuous Source Current (Body Diode)		--	--	40	A
V <sub>SD</sub>	Diode Forward Voltage	I <sub>S</sub> =20A, V <sub>GS</sub> =0V	--	0.85	1.2	V
t <sub>rr</sub>	Reverse Recovery Time	I <sub>S</sub> =20A, T <sub>J</sub> = 25°	--	40	--	ns
Q <sub>rr</sub>	Reverse Recovery Charge	dI <sub>F</sub> /dt=100A/us, V <sub>GS</sub> =0V	--	21	--	nC
Pulse width tp≤380μs, δ≤2%						

### Thermal Characteristics

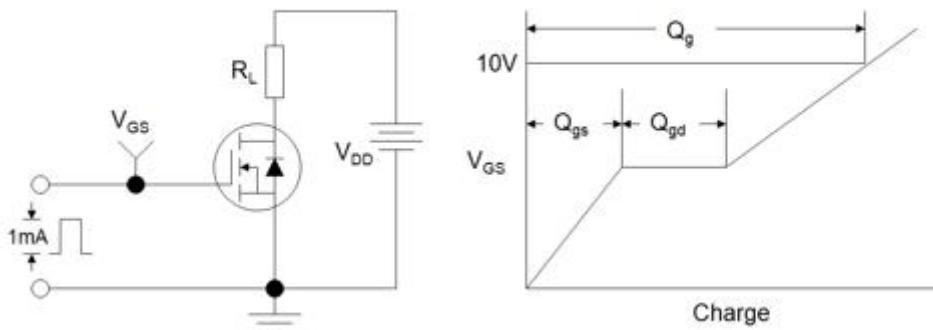
Symbol	Parameter	Typ.	Units
R <sub>θJC</sub>	Junction-to-Case	4.4	°C/W

<sup>a1</sup> : Repetitive rating; pulse width limited by maximum junction temperature

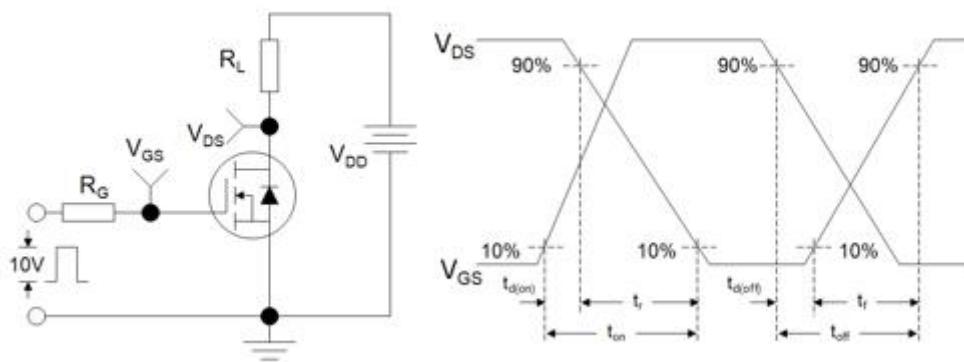
<sup>a2</sup> : L=10.0mH, I<sub>D</sub>=3A, Start T<sub>J</sub>=25°C

<sup>a3</sup> : I<sub>SD</sub> =20A, di/dt ≤100A/us, V<sub>DD</sub>≤BV<sub>DS</sub>, Start T<sub>J</sub>=25°C

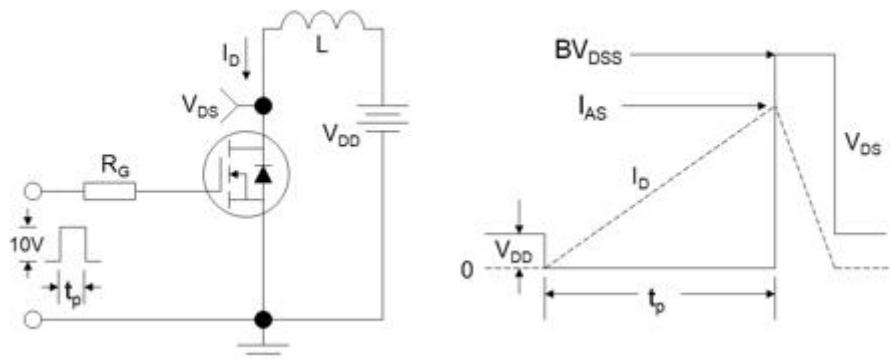
**Figure A: Gate Charge Test Circuit and Waveform**



**Figure B: Resistive Switching Test Circuit and Waveform**



**Figure C: Unclamped Inductive Switching Test Circuit and Waveform**



### Test Circuit and Waveform

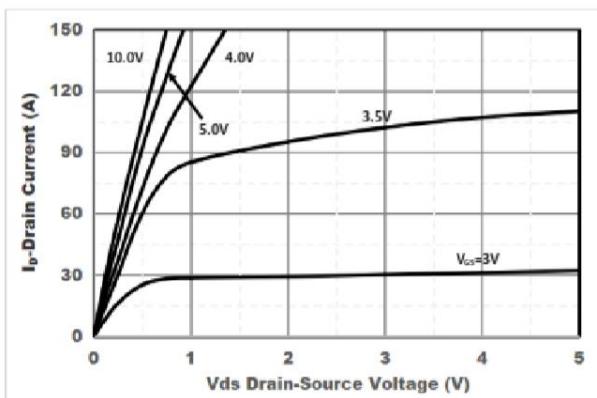
**Characteristics Curve :**

Figure1. Output Characteristics

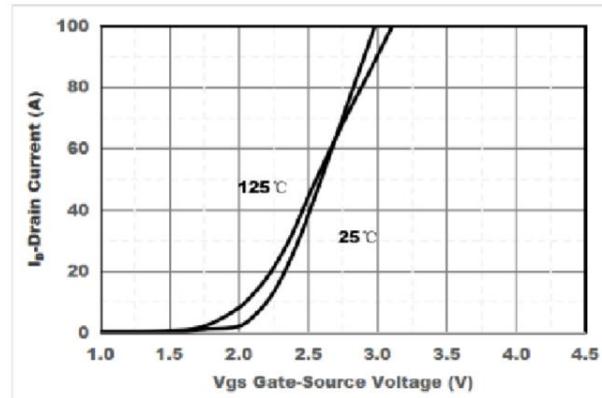


Figure2. Transfer Characteristics

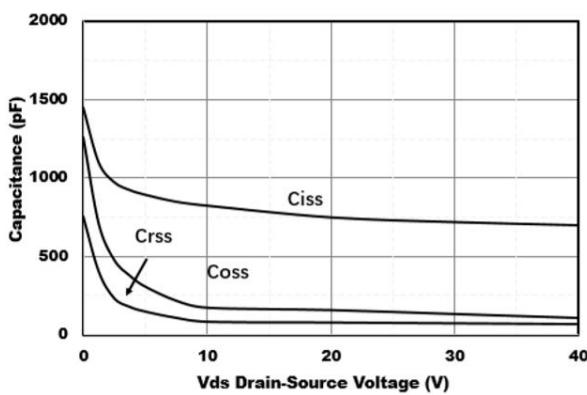


Figure3. Capacitance Characteristics

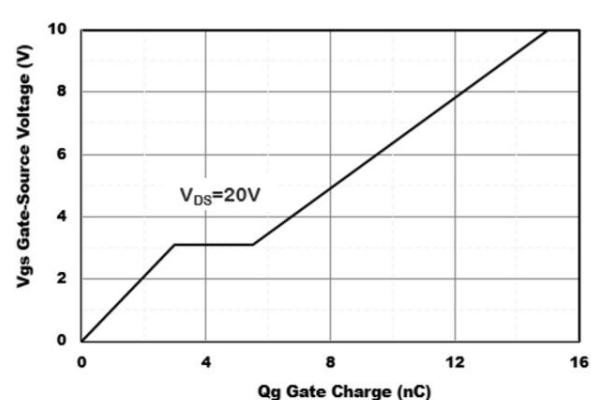


Figure4. Gate Charge

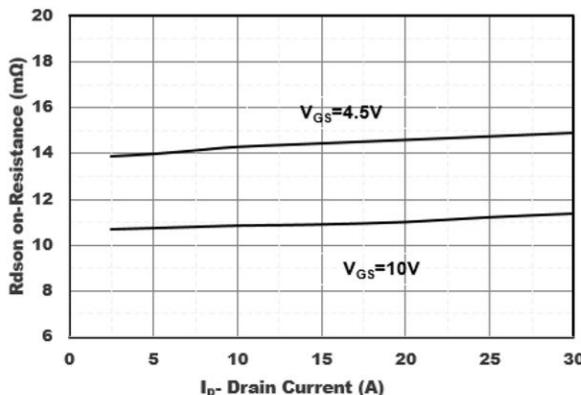


Figure5. Drain-Source on Resistance

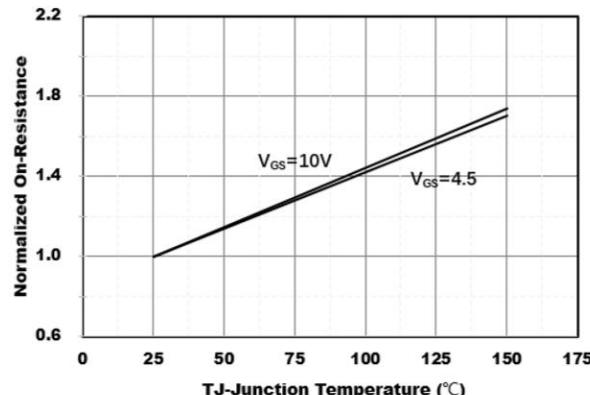


Figure6. Drain-Source on Resistance

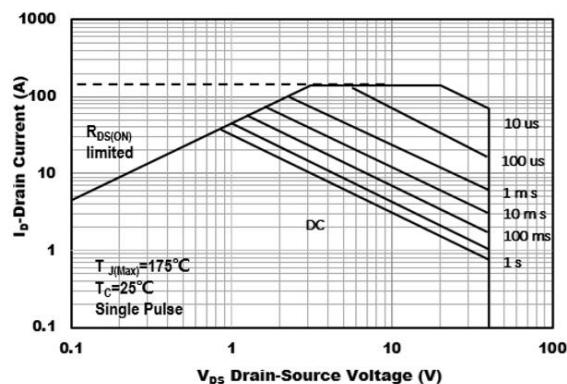


Figure7. Safe Operation Area

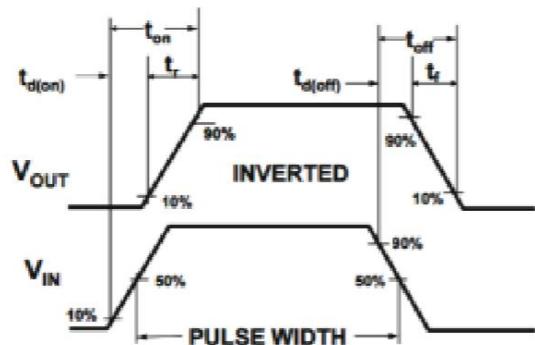


Figure8. Switching wave



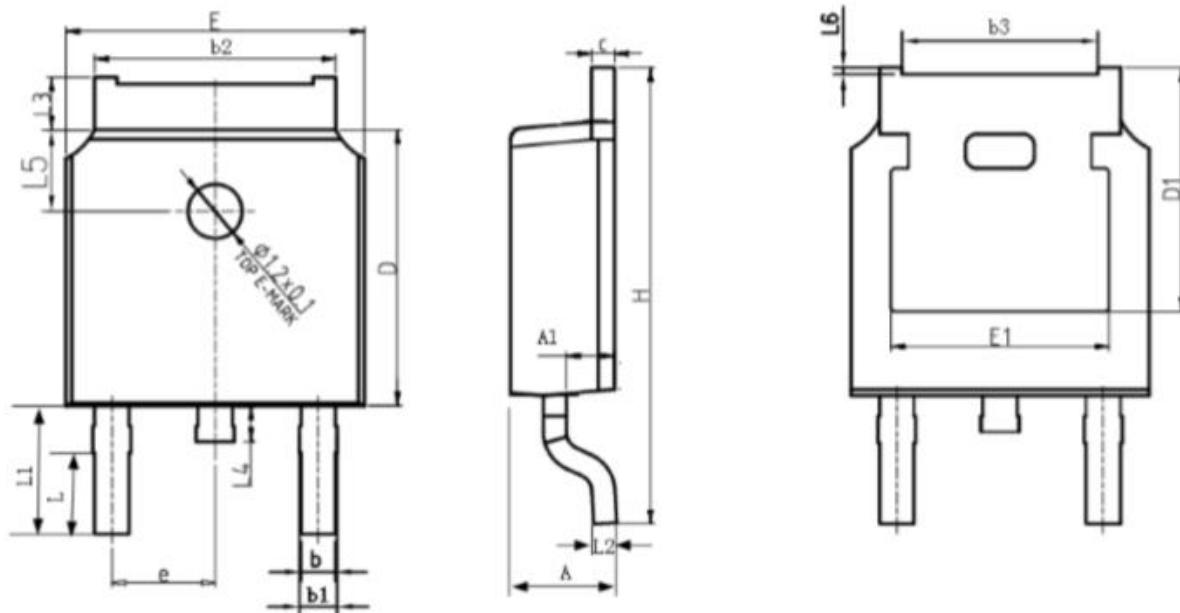
# HMN4013A4

## HM Silicon N-Channel Power MOSFET

### Marking Information

	Part NO.	Part NO.	NO.
●	Y	M	W
Part NO.	HMN4013A4		
●	Pin 1 Indicator		
Lot NO.	Y : Year ; M : Month ; W : Week ; SN : Pipeline Code		

### Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.400	0.056	0.061
A1	0.970	1.17	0.025	0.030
b	0.720	0.850	0.018	0.022
b1	0.720	0.930	0.018	0.024
b2	5.230	5.460	0.133	0.139
b3	4.270	4.370	0.108	0.111
c	0.470	0.580	0.012	0.015
D	6.000	6.200	0.152	0.157
D1	5.300 TYP.		0.135	
E	6.500	6.700	0.165	0.170
E1	4.700	4.920	0.119	0.125
e	2.286 TYP		0.058	
L	1.400	1.700	0.036	0.043
L1	2.900 TYP.		0.074	
L2	0.510 TYP.		0.013	
L3	0.900	1.250	0.023	0.032
L4	0.600	1.000	0.015	0.025
L5	1.700	1.900	0.043	0.048
L6	0	0.1223	0.000	0.003



## Revision History

Revision	Date	Descriptions
REV.1.2	Sep., 2018	"Add Marking Information and Package Information" Update
REV.1.1	Aug., 2018	"Typical Performance Characteristics" Update
REV.1.0	July, 2017	Initial Version